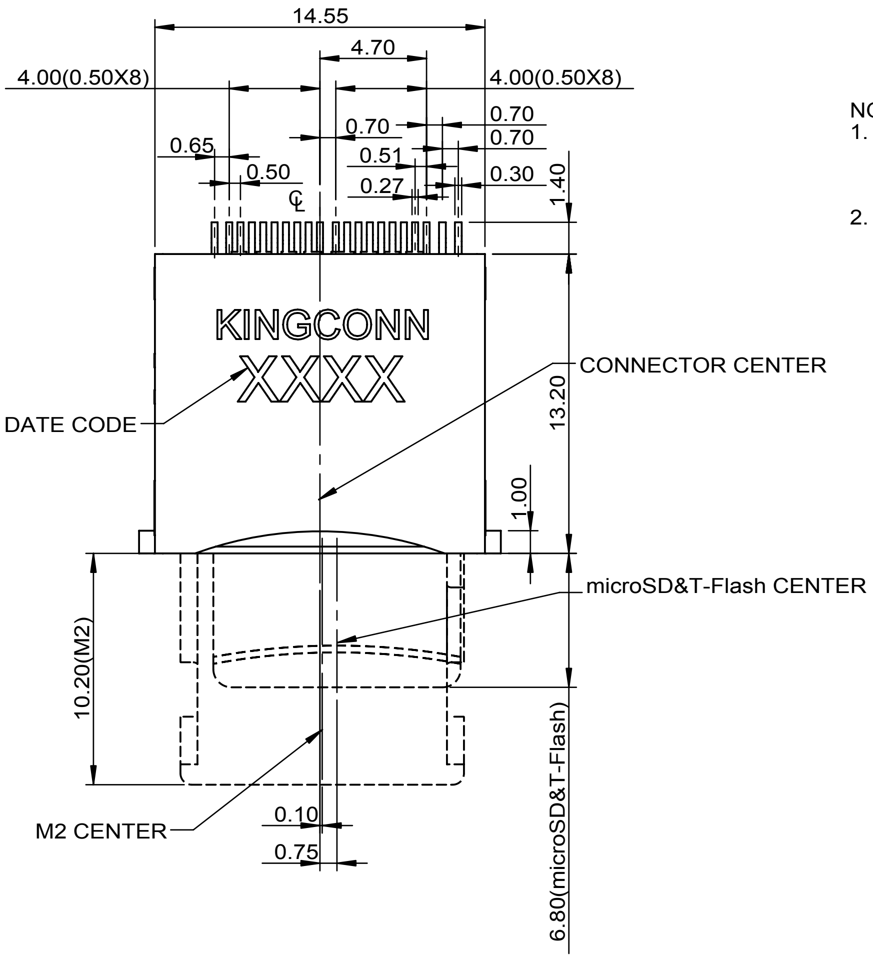
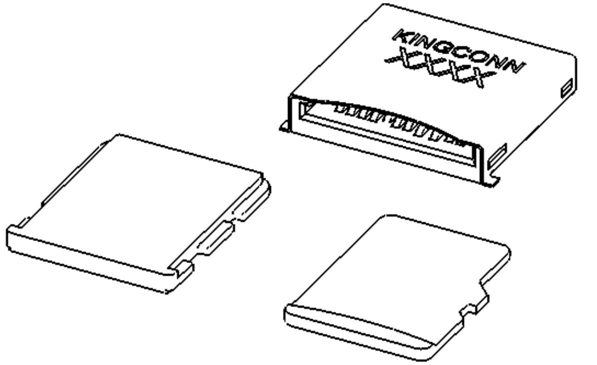
更改 REV	設 變 內 容 MODIFICATION
A	ECN01412
B	ECN01496
C	ECN01997
D	ECN02398
E	ECN02544
F	ECN02816
G	ECN03183

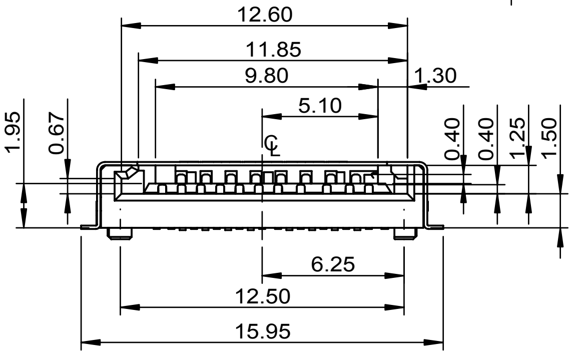


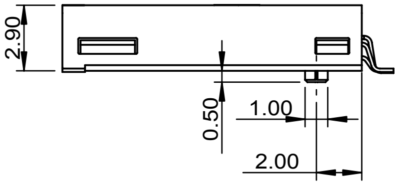
NOTES:
1. MATERIAL:
INSULATOR: HIGH TEMPRATURE THERMOPLASTIC,
UL94V-0,BLACK
CONTACT: PHOSPHOR BRONZE
2. PART NO:7SDM2-X0-X 000

PACKING:
0 :TRAY
1 :TAPE&REEL

PLATING:
F: CONTACT AREA: GOLD FLASH Au PLATED OVER Ni
SOLDER AREA: MATTE Tin PLATED OVER Ni
B: CONTACT AREA: 10μ" Au PLATED OVER Ni
SOLDER AREA: MATTE Tin PLATED OVER Ni







GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°

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名 稱(TITLE) 3 in 1(M2 & microSD&T-Flash)

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	7SDM2-X0-X000	7SDM2-X0-X000-G

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE	張 數 SHEET
			3:1	1/2

角 法 PROJ.

更 改 REV G

更改 REV	設 變 內 容 MODIFICATION
A	ECN01412
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C	ECN01997
D	ECN02398
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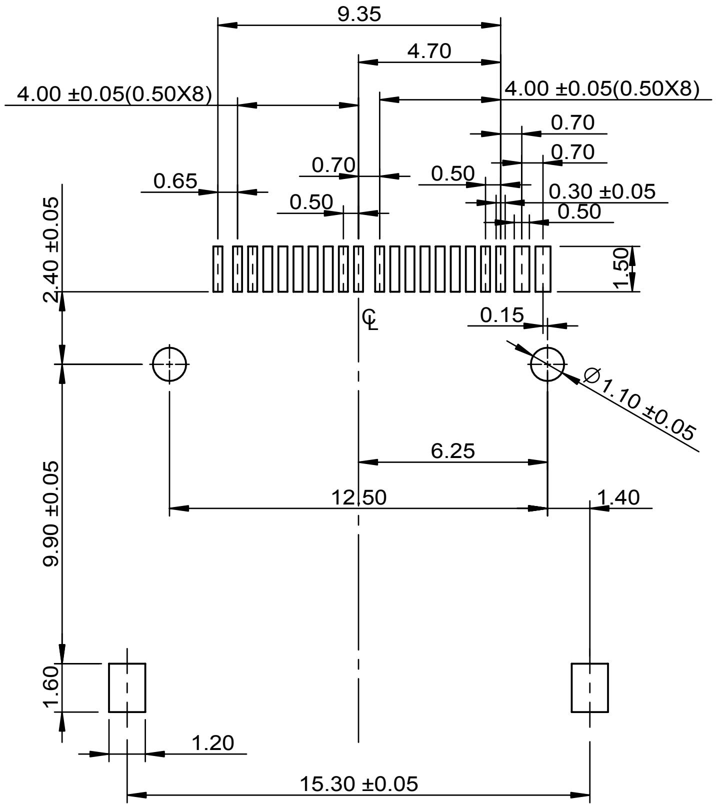

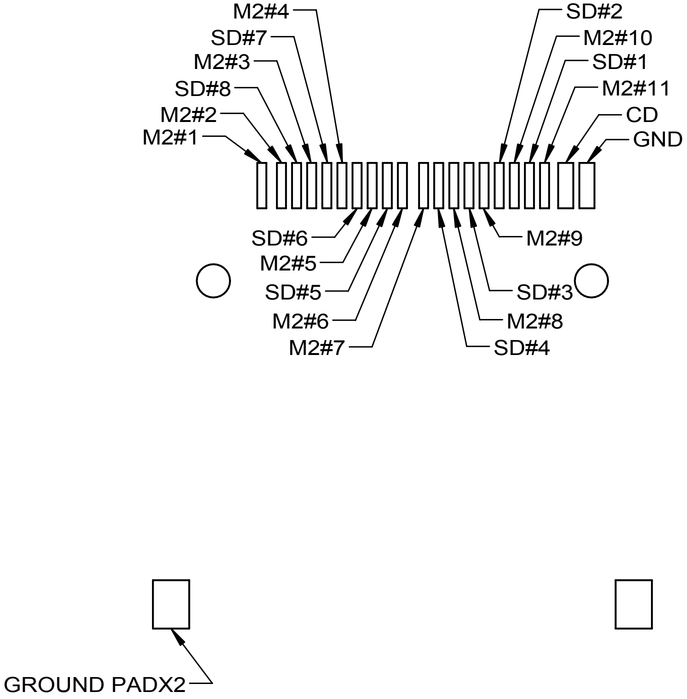

PCB LAYOUT FOR

Pin Assignment:			
M2 #1	BS	SD #1	DTA2
M2 #2	DAT1	SD #2	CD/DAT3
M2 #3	DAT0	SD #3	CMD
M2 #4	DAT2	SD #4	VDD
M2 #5	INS	SD #5	CLK
M2 #6	DAT3	SD #6	VSS
M2 #7	SCLK	SD #7	DAT0
M2 #8	VCC	SD #8	DAT1
M2 #9	VSS		
M2#10	NC/Roscrved		
M2#11	NC/Roscrved		

WITHOUT CARD	microSD&T-Flash CARD INSERTED
CD ○ GROUND ○	CD ○—— — —— — —— — ——○ GROUND

GENERIAL TOLERANCE		**KINGCONN** 皇海科技股份有限公司		
X.± 0.50	X.°± 5°	名 稱(TITLE) 3 in 1(M2 & microSD&T-Flash)		
.X± 0.30	.X°± 2°			
.XX± 0.20	.XX°± 1°			
單 位(UNIT) mm	料 號(PART NO.) 7SDM2-X0-X000		圖 號(DWG NO.) 7SDM2-X0-X000-G	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 4:1	張 數 SHEET 2／2
			角 法 PROJ. ⊕⊐	更 改 REV G

RoHS